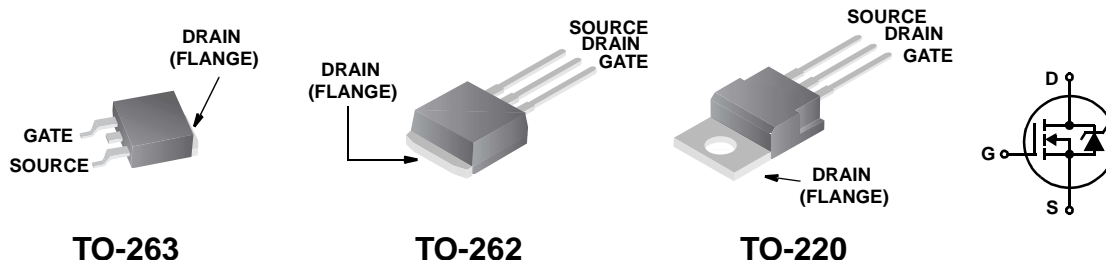# FAIRCHILD

SEMICONDUCTOR®

IRF630N/IRF630NS/IRF630NL

N-Channel Power MOSFETs
200V, 9.3A, 0.30Ω

Features

- Ultra Low On-Resistance
  - $r_{DS(ON)}$ = 0.200Ω (Typ), V_{GS} = 10V
- Simulation Models
  - Temperature Compensated PSPICE® and SABER© Electrical Models
  - Spice and SABER© Thermal Impedance Models

- Peak Current vs Pulse Width Curve
- UIS Rating Curve

TO-263   **TO-262**   **TO-220**

MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	200	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Drain Current		
	Continuous (T_C = 25°C, V_{GS} = 10V)	9.3	A
	Continuous (T_C = 100°C, V_{GS} = 10V)	6.5	A
	Pulsed	Figure 4	A
E_{AS}	Single Pulse Avalanche Energy (Note 1)	94	mJ
P_D	Power dissipation	82	W
	Derate above 25°C	0.55	W/°C
T_J, T_{STG}	Operating and Storage Temperature	-55 to 175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case TO-220, TO-262, TO-263	1.83	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-220, TO-262, TO-263	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263, 1in² copper pad area	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
630N	IRF630NS	TO-263AB	330mm	24mm	800 units
630N	IRF630NL	TO-262AA	Tube	N/A	50
630N	IRF630N	TO-220AB	Tube	N/A	50

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min	Typ	Max	Units
Off Characteristics							
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu A$, $V_{GS} = 0V$		200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 200V$	$V_{GS} = 0V$	-	-	25	μA
		$V_{DS} = 160V$	$T_C = 150^o$	-	-	250	
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm20V$		-	-	±100	nA
On Characteristics							
$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\mu A$		2	-	4	V
$r_{DS(ON)}$	Drain to Source On Resistance	$I_D = 5.4A$, $V_{GS} = 10V$		-	0.200	0.300	Ω
g_{fs}	Forward Transconductance	$V_{DS} = 50V$, $I_D = 5.4A$ (Note 2)		49	-	-	S
Dynamic Characteristics							
C_{ISS}	Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, f = 1MHz		-	1030	-	pF
C_{OSS}	Output Capacitance			-	120	-	pF
C_{RSS}	Reverse Transfer Capacitance			-	50	-	pF
$Q_{g(TOT)}$	Total Gate Charge at 20V	$V_{GS} = 0V$ to 20V	$V_{DD} = 100V$ $I_D = 11A$ $I_g = 1.0mA$		59	78	nC
$Q_{g(10)}$	Total Gate Charge at 10V	$V_{GS} = 0V$ to 10V		-	32	42	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0V$ to 2V		-	2.0	3.2	nC
Q_{gs}	Gate to Source Gate Charge			-	4.0	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	11	-	nC
Switching Characteristics ($V_{GS} = 10V$)							
t_{ON}	Turn-On Time	$V_{DD} = 100V$, $I_D = 5.4A$ $V_{GS} = 10V$, $R_{GS} = 13\Omega$		-	-	32	ns
$t_{d(ON)}$	Turn-On Delay Time			-	9	-	ns
t_r	Rise Time			-	12	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time			-	71	-	ns
t_f	Fall Time			-	19	-	ns
t_{OFF}	Turn-Off Time			-	-	135	ns
Drain-Source Diode Characteristics							
V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 5.4A$		-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 5.4A$, $dI_{SD}/dt = 100A/\mu s$		-	-	176	ns
Q_{RR}	Reverse Recovered Charge	$I_{SD} = 5.4A$, $dI_{SD}/dt = 100A/\mu s$		-	-	813	nC

Notes:
1: Starting T_J = 25°C, L = 6.5mH, I_{AS} = 5.4A.
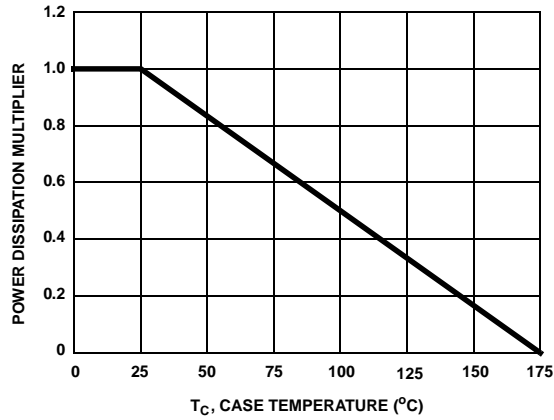**2:** Pulse width ≤ 400μs; duty cycle ≤ 2%.`

Typical Characteristic

Figure 1. Normalized Power Dissipation vs Ambient Temperature

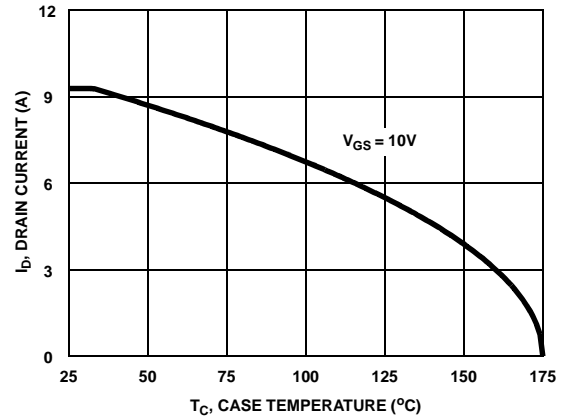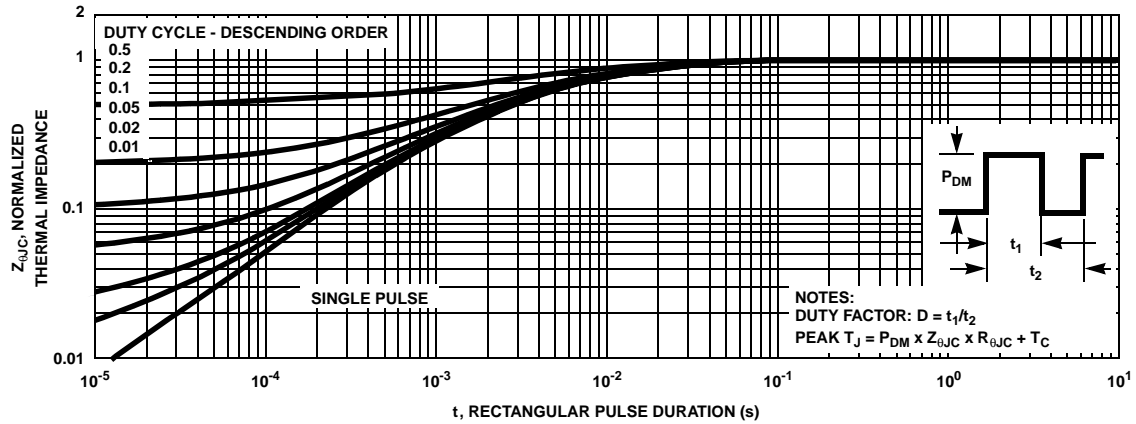Figure 2. Maximum Continuous Drain Current vs Case Temperature

DUTY CYCLE - DESCENDING ORDER
0.5
0.2
0.1
0.05
0.02
0.01

SINGLE PULSE

P_{DM}

t_1

t_2

NOTES:
DUTY FACTOR: $D = t_1/t_2$
PEAK $T_J = P_{DM} \times Z_{\theta JC} \times R_{\theta JC} + T_C$

Figure 3. Normalized Maximum Transient Thermal Impedance

$T_C = 25^oC$
FOR TEMPERATURES
ABOVE 25°C DERATE PEAK
CURRENT AS FOLLOWS:

$$I = I_{25} \left[\sqrt{\frac{175 - T_C}{150}} \right]$$

$V_{GS} = 10V$

TRANSCONDUCTANCE
MAY LIMIT CURRENT
IN THIS REGION
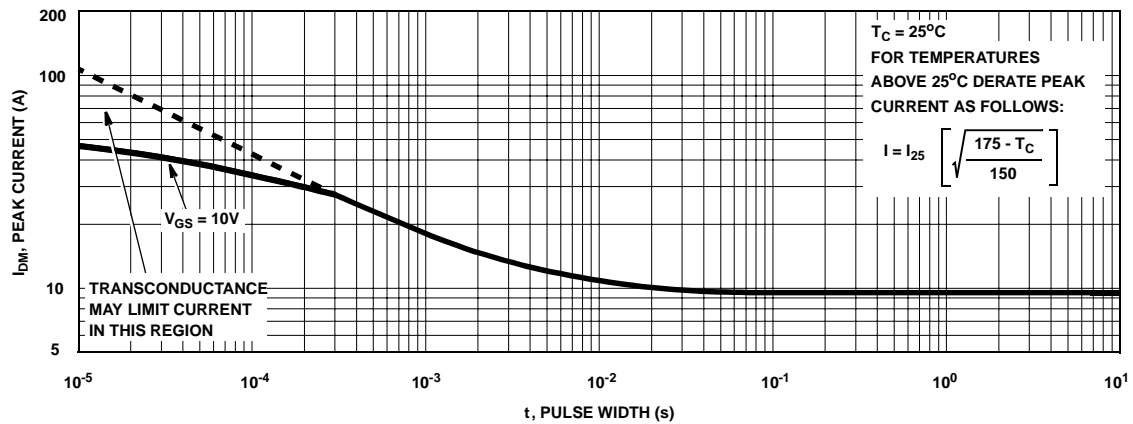
Figure 4. Peak Current Capability

Typical Characteristic (Continued)
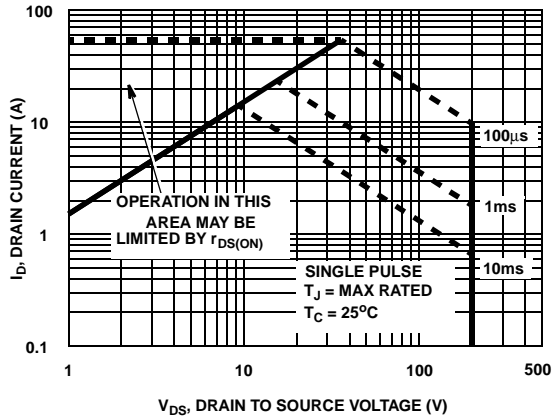
Figure 5. Forward Bias Safe Operating Area

If R = 0
$t_{AV} = (L)(I_{AS})/(1.3*RATED\ BV_{DSS} - V_{DD})$
If R ≠ 0
$t_{AV} = (L/R)ln[(I_{AS}*R)/(1.3*RATED\ BV_{DSS} - V_{DD}) +1]$

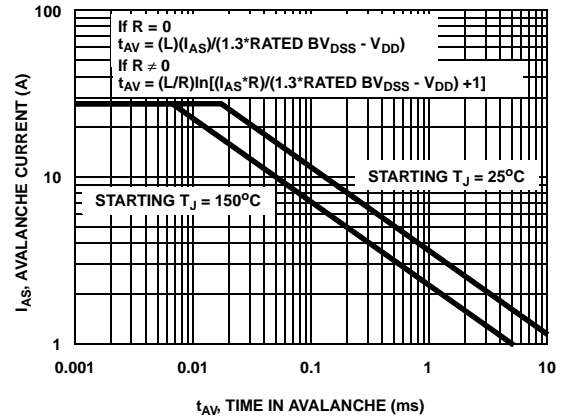**Figure 6. Unclamped Inductive Switching Capability**
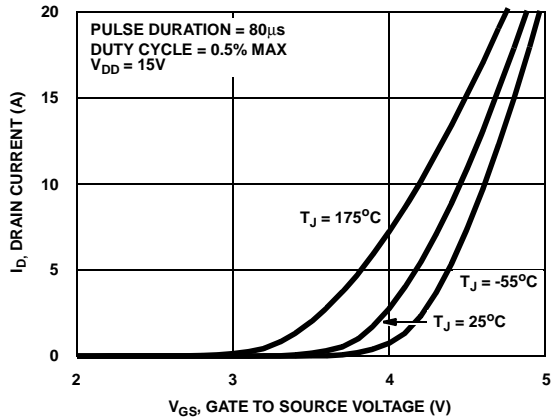

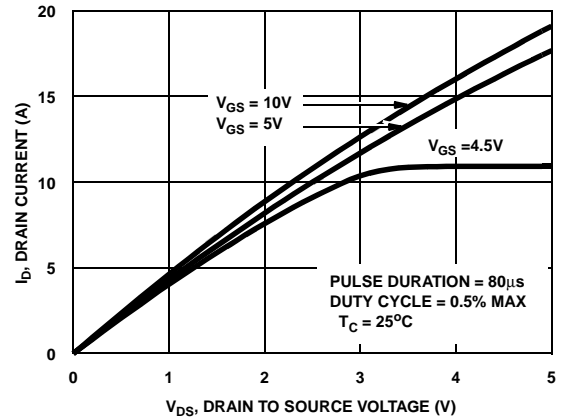**Figure 7. Transfer Characteristics**
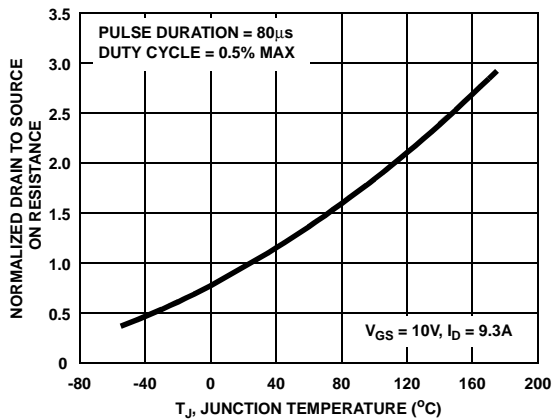

Figure 8. Saturation Characteristics

Figure 9. Normalized Drain to Source On Resistance vs Junction Temperature
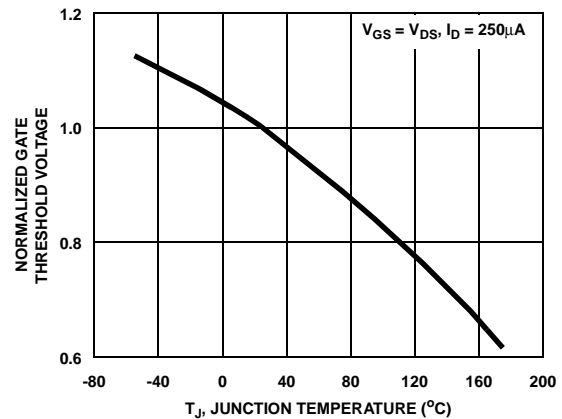

Figure 10. Normalized Gate Threshold Voltage vs Junction Temperature

Typical Characteristic (Continued)
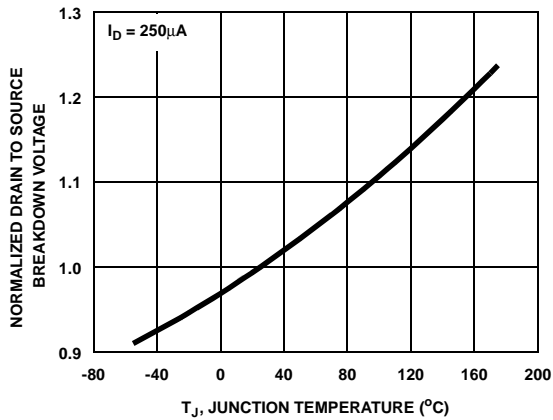
Figure 11. Normalized Drain to Source Breakdown Voltage vs Junction Temperature
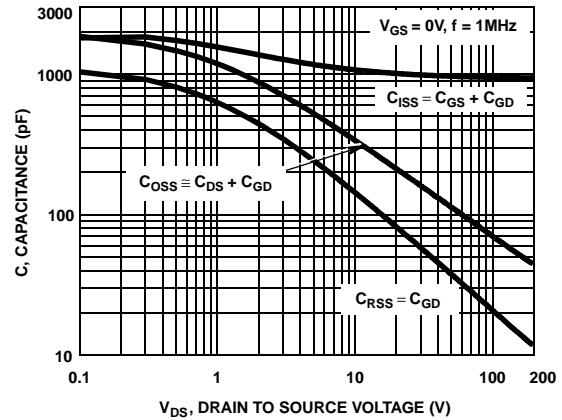
Figure 12. Capacitance vs Drain to Source Voltage

Figure 13. Gate Charge Waveforms for Constant Gate Currents

Test Circuits and Waveforms

Figure 14. Unclamped Energy Test Circuit

Figure 15. Unclamped Energy Waveforms

Test Circuits and Waveforms (Continued)

Figure 16. Gate Charge Test Circuit

Figure 17. Gate Charge Waveforms

Figure 18. Switching Time Test Circuit

Figure 19. Switching Time Waveforms

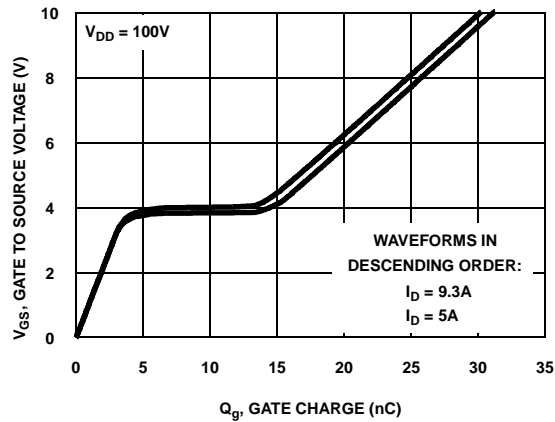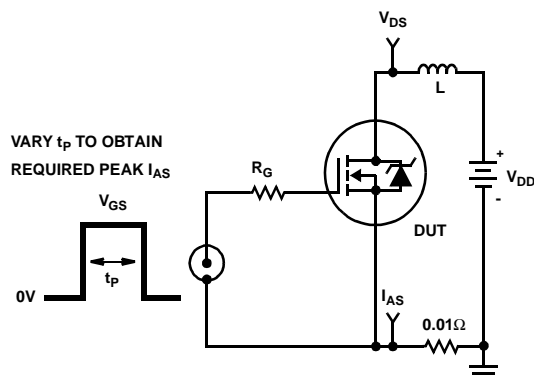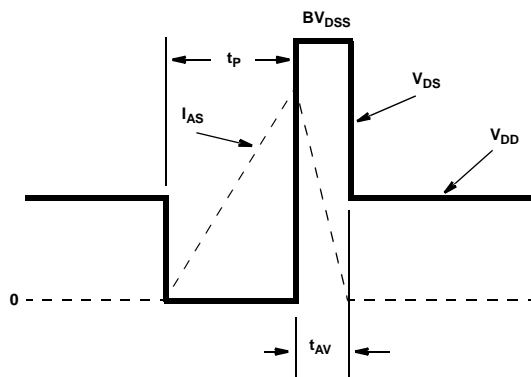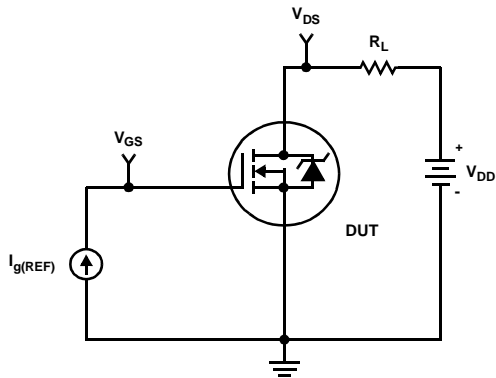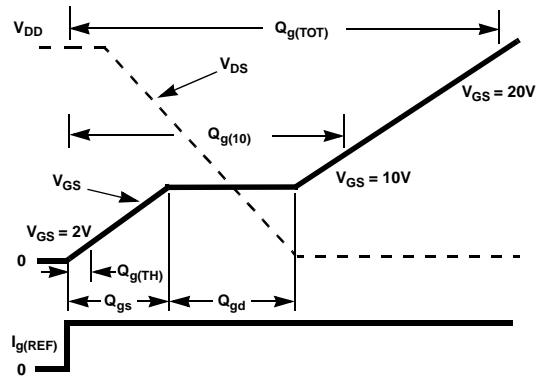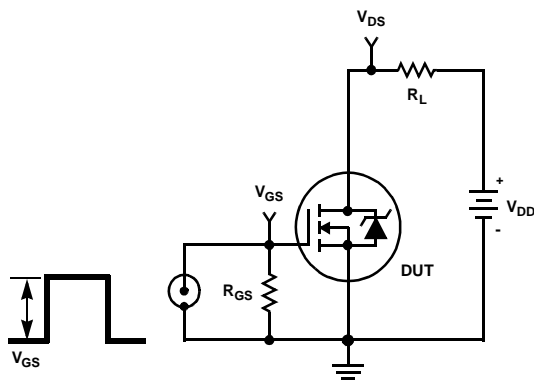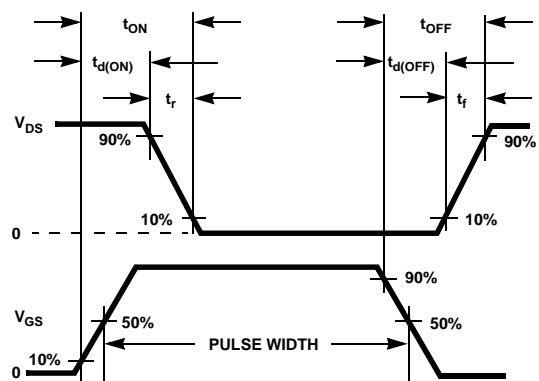## *Thermal Resistance vs. Mounting Pad Area*

The maximum rated junction temperature, T_{JM}, and the thermal resistance of the heat dissipating path determines the maximum allowable device power dissipation, P_{DM}, in an application. Therefore the application's ambient temperature, T_A (^oC), and thermal resistance $R_{\theta JA}$ ($^oC/W$) must be reviewed to ensure that T_{JM} is never exceeded. Equation 1 mathematically represents the relationship and serves as the basis for establishing the rating of the part.

$$P_{DM} = \frac{(T_{JM} - T_A)}{Z_{\theta JA}} \qquad \text{(EQ. 1)}$$

In using surface mount devices such as the TO-263 package, the environment in which it is applied will have a significant influence on the part's current and maximum power dissipation ratings. Precise determination of P_{DM} is complex and influenced by many factors:

1. Mounting pad area onto which the device is attached and whether there is copper on one side or both sides of the board.

2. The number of copper layers and the thickness of the board.

3. The use of external heat sinks.

4. The use of thermal vias.

5. Air flow and board orientation.

6. For non steady state applications, the pulse width, the duty cycle and the transient thermal response of the part, the board and the environment they are in.

Fairchild provides thermal information to assist the designer's preliminary application evaluation. Figure 20 defines the $R_{\theta JA}$ for the device as a function of the top copper (component side) area. This is for a horizontally positioned FR-4 board with 1oz copper after 1000 seconds of steady state power with no air flow. This graph provides the necessary information for calculation of the steady state junction temperature or power dissipation. Pulse applications can be evaluated using the Fairchild device Spice thermal model or manually utilizing the normalized maximum transient thermal impedance curve.

Displayed on the curve are $R_{\theta JA}$ values listed in the Electrical Specifications table. The points were chosen to depict the compromise between the copper board area, the thermal resistance and ultimately the power dissipation, P_{DM}.

Thermal resistances corresponding to other copper areas can be obtained from Figure 20 or by calculation using Equation 2. $R_{\theta JA}$ is defined as the natural log of the area times a coefficient added to a constant. The area, in square inches is the top copper area including the gate and source pads.

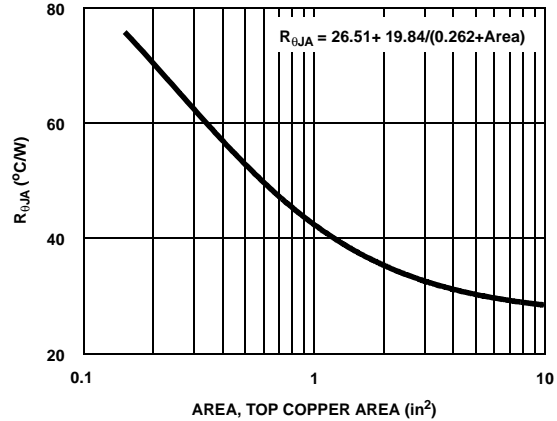$$R_{\theta JA} = 26.51 + \frac{19.84}{(0.262 + Area)} \qquad \text{(EQ. 2)}$$

Figure 20. Thermal Resistance vs Mounting Pad Area

PSPICE Electrical Model

.SUBCKT IRF630N 2 1 3 ;   rev May 2001

CA 12 8 1.6e-9
CB 15 14 1.75e-9
CIN 6 8 9.3e-8

DBODY 7 5 DBODYMOD
DBREAK 5 11 DBREAKMOD
DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 227
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTHRES 6 21 19 8 1
EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1e-9
LGATE 1 9 5.12e-9
LSOURCE 3 7 4.24e-9

MMED 16 6 8 8 MMEDMOD
MSTRO 16 6 8 8 MSTROMOD
MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1
RDRAIN 50 16 RDRAINMOD 1.98e-1
RGATE 9 20 1.61
RLDRAIN 2 5 10
RLGATE 1 9 51.2
RLSOURCE 3 7 42.4
RSLC1 5 51 RSLCMOD 1e-6
RSLC2 5 50 1e3
RSOURCE 8 7 RSOURCEMOD 1e-2
RVTHRES 22 8 RVTHRESMOD 1
RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*19),2.5))}

.MODEL DBODYMOD D (IS = 1e-12 N=1.02 RS = 7.75e-3 TRS1 = 2.5e-3 TRS2 = 2e-5 CJO = 8.5e-10 TT = 9.6e-6 M = 0.61 XTI=5.5)
.MODEL DBREAKMOD D (RS = 4. 2TRS1 = 1e- 3TRS2 = -8.9e-6)
.MODEL DPLCAPMOD D (CJO = 1.15e- 9IS = 1e-30 N = 10 M = 0.86)
.MODEL MMEDMOD NMOS (VTO = 3.25 KP = 5 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 1.61)
.MODEL MSTROMOD NMOS (VTO = 3.65 KP = 28 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
.MODEL MWEAKMOD NMOS (VTO = 2.8 KP = 0.05 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 16.1 RS=.1)
.MODEL RBREAKMOD RES (TC1 =1.3e- 3TC2 = 2e-6)
.MODEL RDRAINMOD RES (TC1 = 1e- 2TC2 = 3.7e-5)
.MODEL RSLCMOD RES (TC1 = 4e-3 TC2 = 1e-6)
.MODEL RSOURCEMOD RES (TC1 = 1e-3 TC2 = 1e-6)
.MODEL RVTHRESMOD RES (TC1 = -2e-3 TC2 = -1.3e-5)
.MODEL RVTEMPMOD RES (TC1 = -3e- 3TC2 = 1.9e-6)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -7.5 VOFF= -.5)
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -.5 VOFF= -7.5)
.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -0.1 VOFF= 0.2)
.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.2 VOFF= -0.1)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

SABER Electrical Model

REV May 2001

```
template IRF630N n2,n1,n3
electrical n2,n1,n3
{
var i iscl
dp..model dbodymod =  (isl = 1e-12, rs = 7.75e-3, xti = 5.5, trs1 = 2.5e-3, trs2 = 2e-5, cjo = 8.5e-10, tt = 9.6e-6, m = 0.61)
dp..model dbreakmod = (rs = 4.2, trs1 = 1e-3, trs2 = -8.9e-6)
dp..model dplcapmod =  (cjo = 1.15e-9, isl = 10e-30, nl=10, m = 0.86)
m..model mmedmod = (type=_n, vto = 3.25, kp = 5, isl = 1e-30, tox = 1)
m..model mstrongmod = (type=_n, vto = 3.65, kp = 28, isl = 1e-30, tox = 1)
m..model mweakmod = (type=_n, vto = 2.8, kp = 0.05, isl = 1e-30, tox = 1, rs=0.1)
sw_vcsp..model s1amod =  (ron = 1e-5, roff = 0.1, von = -7.5, voff = -.5)
sw_vcsp..model s1bmod =  (ron =1e-5, roff = 0.1, von = -.5, voff = -7.5)
sw_vcsp..model s2amod =  (ron = 1e-5, roff = 0.1, von = -0.1, voff = 0.2)
sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.2, voff = -0.1)

c.ca n12 n8 = 1.6e-9
c.cb n15 n14 = 1.75e-9
c.cin n6 n8 = 9.3e-8

dp.dbody n7 n5 = model=dbodymod
dp.dbreak n5 n11 = model=dbreakmod
dp.dplcap n10 n5 = model=dplcapmod

i.it n8 n17 = 1

l.ldrain n2 n5 = 1e-9
l.lgate n1 n9 = 5.12e-9
l.lsource n3 n7 = 4.24e-9

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u
m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u
m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

res.rbreak n17 n18  = 1, tc1 = 1.3e-3, tc2 = 2e-6
res.rdrain n50 n16 = 1.98e-5, tc1 = 1e-2, tc2 =3.7e-5
res.rgate n9 n20 = 1.61
res.rldrain n2 n5 = 10
res.rlgate n1 n9 = 51.2
res.rlsource n3 n7 = 42.4
res.rslc1 n5 n51= 1e-6, tc1 = 4e-3, tc2 = -1e-6
res.rslc2 n5 n50 = 1e3
res.rsource n8 n7 = 10e-3, tc1 = 1e-3, tc2 =1e-6
res.rvtemp n18 n19 = 1, tc1 = -2e-3, tc2 = -1.3e-5
res.rvthres n22 n8 = 1, tc1 = -3e-3, tc2 = 1.9e-6

spe.ebreak n11 n7 n17 n18 = 227
spe.eds n14 n8 n5 n8 = 1
spe.egs n13 n8 n6 n8 = 1
spe.esg n6 n10 n6 n8 = 1
spe.evtemp n20 n6 n18 n22 = 1
spe.evthres n6 n21 n19 n8 = 1

sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod
sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod
sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod
sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

v.vbat n22 n19 = dc=1

equations {
i (n51->n50) +=iscl
iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6*19))** 2.5))
}
}
```

SPICE Thermal Model

REV May 2001

IRF630N

CTHERM1 th 6 8.0e-4
CTHERM2 6 5 2.6e-3
CTHERM3 5 4 3.5e-3
CTHERM4 4 3 5.2e-3
CTHERM5 3 2 7.0e-3
CTHERM6 2 tl 3.3e-2

RTHERM1 th 6 1.0e-3
RTHERM2 6 5 4.5e-3
RTHERM3 5 4 4.2e-2
RTHERM4 4 3 2.5e-1
RTHERM5 3 2 3.9e-1
RTHERM6 2 tl 5.0e-1

SABER Thermal Model

SABER thermal model IRF630N

template thermal_model th tl
thermal_c th, tl
{
ctherm.ctherm1 th 6 = 8.0e-4
ctherm.ctherm2 6 5 = 2.6e-3
ctherm.ctherm3 5 4 = 3.5e-3
ctherm.ctherm4 4 3 = 5.2e-3
ctherm.ctherm5 3 2 = 7.0e-3
ctherm.ctherm6 2 tl = 3.3e-2

rtherm.rtherm1 th 6 = 1.0e-3
rtherm.rtherm2 6 5 = 4.5e-3
rtherm.rtherm3 5 4 = 4.2e-2
rtherm.rtherm4 4 3 = 2.5e-1
rtherm.rtherm5 3 2 = 3.9e-1
rtherm.rtherm6 2 tl = 5.0e-1
}
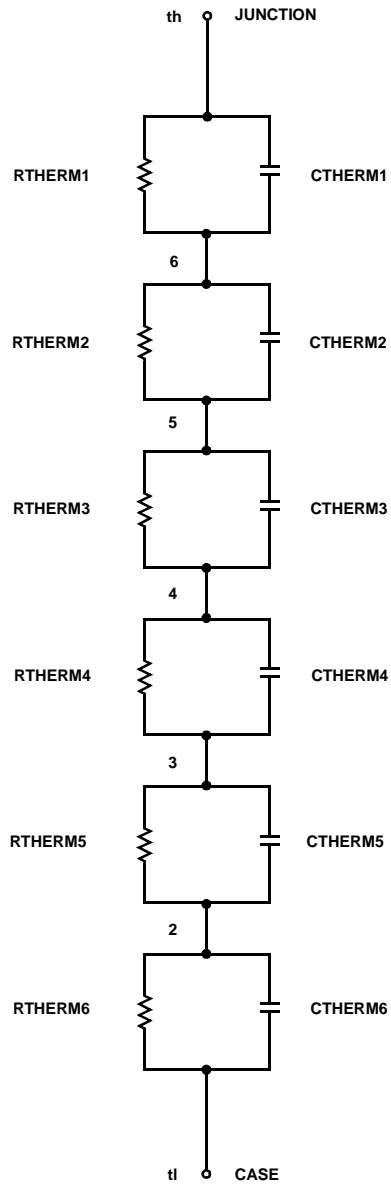
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CROSSVOLT™	GlobalOptoisolator™	POP™	SuperSOT™-3
DenseTrench™	GTO™	Power247™	SuperSOT™-6
DOME™	HiSeC™	PowerTrench ®	SuperSOT™-8
EcoSPARK™	ISOPLANAR™	QFET™	SyncFET™
E²CMOS™	LittleFET™	QS™	TinyLogic™
EnSigna™	MicroFET™	QT Optoelectronics™	TruTranslation™
FACT™	MicroPak™	Quiet Series™	UHC™
FACT Quiet Series™	MICROWIRE™	SILENT SWITCHER ®	UltraFET ®

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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